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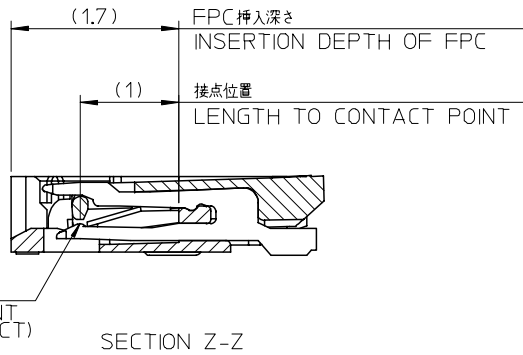
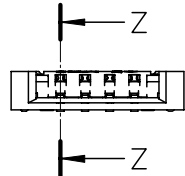
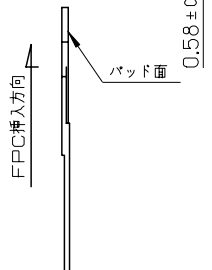
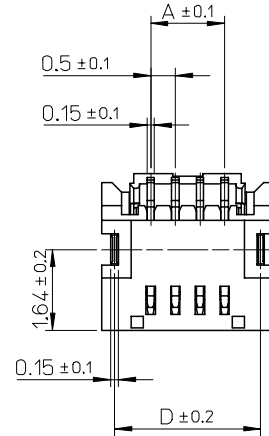
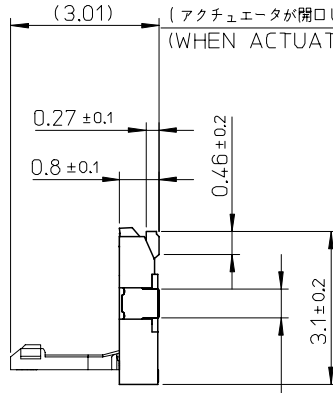
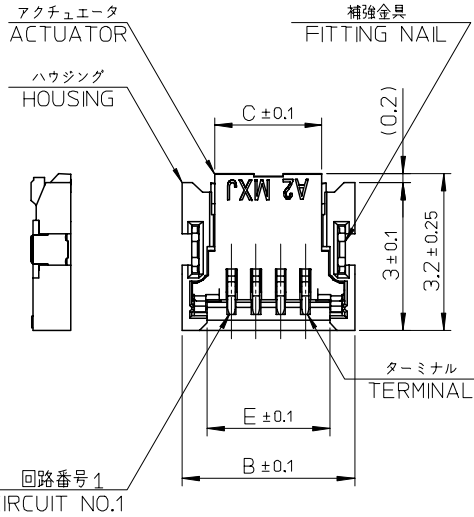
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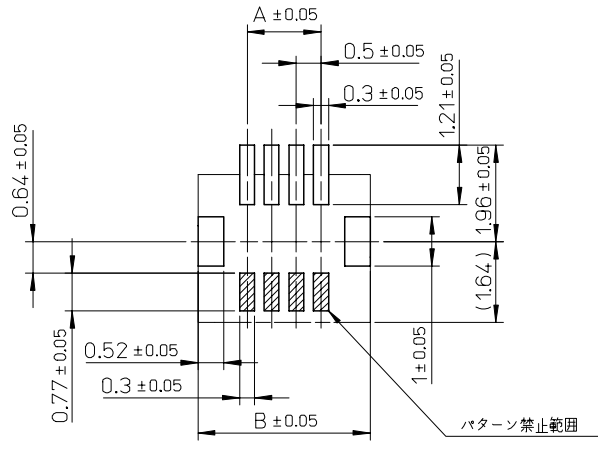


注記
NOTES:

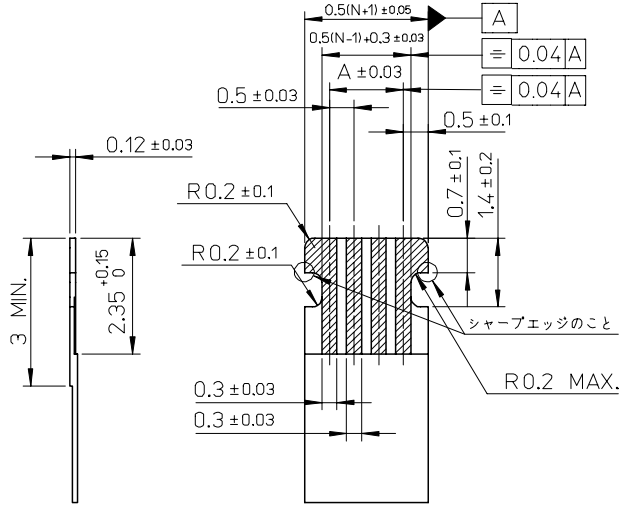
- 材質
MATERIAL
ハウジング:耐熱性樹脂、ガラス充填、UL94V-0
HOUSING:HEAT RESISTANCE POLYMER, GLASS FILLED, UL94V-0
アクチュエータ:耐熱性樹脂、ガラス充填、UL94V-0
ACTUATOR:HEAT RESISTANCE POLYMER, GLASS FILLED, UL94V-0
ターミナル:銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
補強金具:銅合金 (t=0.15)
NAIL: COPPER ALLOY (t=0.15)
- めっき仕様
PLATING
ターミナル: 部分金メッキ
Terminal: Partial Gold Plating
接点部 0.1マイクロメートル以上
Contact Area 0.1 MICROMETER MINIMUM.
半田付け部 0.05マイクロメートル以上
Solder Tail Area 0.05 MICROMETER MINIMUM.
TERMINAL: SEPARATED GOLD PLATING
CONTACT AREA 0.1 MICROMETER MINIMUM.
SOLDER TAIL AREA 0.05 MICROMETER MINIMUM.
下地 ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING; NICKEL PLATING 1.0 MICROMETER MINIMUM.
補強金具: 錫メッキ 1.0マイクロメートル以上
NAIL: TIN PLATING 1.0 MICROMETER MINIMUM.
下地 ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING; NICKEL PLATING 1.0 MICROMETER MINIMUM.
- 平坦度は、0.1mm以下とする。
TAILS AND NAILS COPLANARITY TO BE 0.1mm MAXIMUM.

4.5	4.97	4.18	5.5	3.5	501461-0801	501461-0809	8
4.0	4.47	3.68	5.0	3.0	NOT AVAILABLE	NOT AVAILABLE	7
3.5	3.97	3.18	4.5	2.5	501461-0601	501461-0609	6
3.0	3.47	2.68	4.0	2.0	501461-0501	501461-0509	5
2.5	2.97	2.18	3.5	1.5	501461-0401	501461-0409	4
E	D	C	B	A	エンボス梱包品 EMBOSSED PACKAGING	製品番号 MATERIAL NO.	極数(N) CIRCUITS(N)

REVISED EC NO: J2006-2218 DRW:RSUMIYA 2006/01/10 CHKD:HIRATA 2006/01/11 APPR:HIRATA 2006/01/13 REV DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY RSUMIYA		TITLE 0.5 FPC CONN BACK FLIP HGT=0.8 HSG ASSY -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY HIRATA		MATERIAL NO. SEE CHART		
	30 OVER	±0.3	APPROVED BY MSASAO		DOCUMENT NO. SD-501461-001		
ANGULAR ±1		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SHEET NO. 1 OF 2		MOLEX INCORPORATED	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



推奨基板寸法
RECOMMENDED P.C. BOARD PATTERN LAYOUT

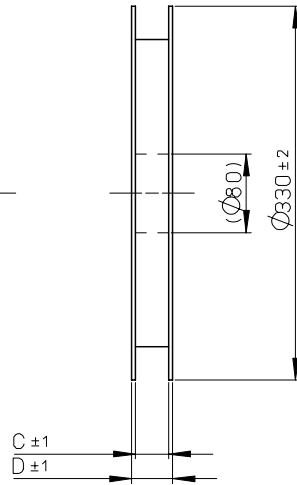
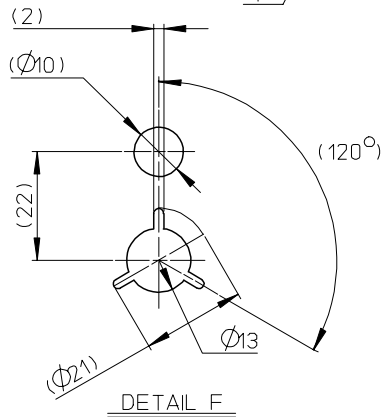
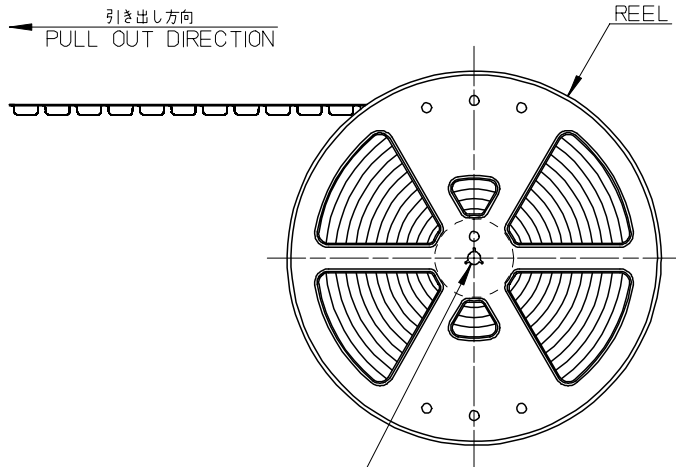


推奨FPC寸法
RECOMMENDED FPC PATTERN LAYOUT

FPCについて:
 抜き方向は、導体側から補強板側を推奨します。
 補強フィルム材質は、ポリイミドを推奨します。
 接着剤は、熱硬化接着剤を推奨します。
 尚、接着剤の接点部への付着は、導通不良の原因となりますので染み出しが無いよう、お願いします。

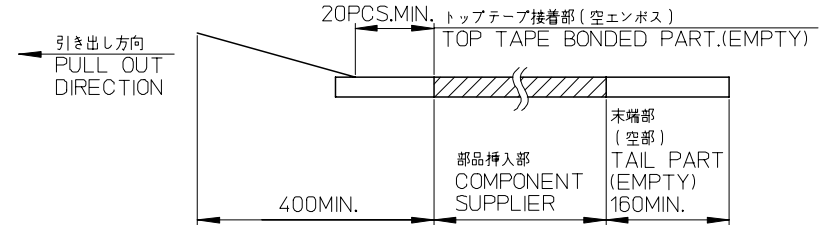
ABOUT FPC:
 RECOMMENDED PUNCHER DIRECTION:
 FROM CONDUCTOR SIDE TO STIFFNER FILME SIDE.
 RECOMMENDED MATERIAL:
 STIFFNER FILME: POLYIMIDE
 BONDING AGENT: THRMOSSETTING AGENT
 PLEASE PUT APPROPRIATE AMOUNT OF ASHESIVE MAY CAUSE
 THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO: J2006-2218 DRWR:RSUMIYA 2006/01/10 CHKD:HIRATA 2006/01/11 APPR:HIRATA 2006/01/13	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY RSUMIYA	DATE 2004/11/10	TITLE 0.5 FPC CONN BACK FLIP HGT=0.8 HSG ASSY -LEAD FREE-			
		10 OVER 30 UNDER	± 0.25	CHECKED BY HIRATA	DATE 2004/11/10	MOLEX INCORPORATED			
		30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2004/11/10				
		ANGULAR	± 1	MATERIAL NO.	DOCUMENT NO. SD-501461-001	SHEET NO. 2 OF 2			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

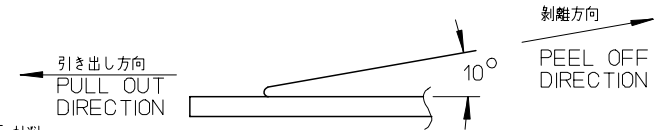


NOTES

1. 製品詳細寸法については製品単体図面を参照下さい。
RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
2. 梱包数量: 3000個/リール
NUMBER OF CONNECTORS 3000PCS/REEL
3. リードテープ長さ
LEAD TAPE LENGTH



4. トップテープの剥離強度: $0.1N \sim 1.3N$ { $10gf \sim 130gf$ }
(剥離強度は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : $0.1N \sim 1.3N(10gf \sim 130gf)$
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.



5. 材料
MATERIAL
キャリアテープ(CARRIRE TAPE): ホリスチレン (POLYSTYRENE)
トップテープ(TOP TAPE): PET, PE, PEF
リール(REEL): ホリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>

501461-**01 MODEL NO.

REVISED EC NO: J2006-2822 DRW:RSUMIYA 2006/03/08 CHKD:HIRATA 2006/03/08 APPR:HIRATA 2006/03/10	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY RSUMIYA	DATE 2005/02/07	TITLE 0.5 FPC CONN BACK FLIP H=0.8 EMBSTP PKG -LEAD FREE-			
		10 OVER 30 UNDER	± 0.25	CHECKED BY HIRATA	DATE 2005/02/07	MOLEX INCORPORATED			
		30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2005/02/07	DOCUMENT NO. SD-501461-002			
		ANGULAR	$\pm 1^\circ$	MATERIAL NO. SEE CHART		SHEET NO. 1 OF 2			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

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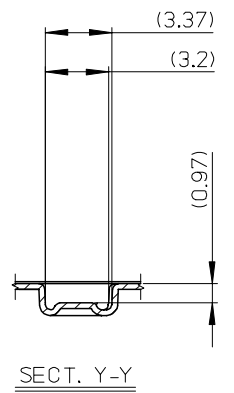
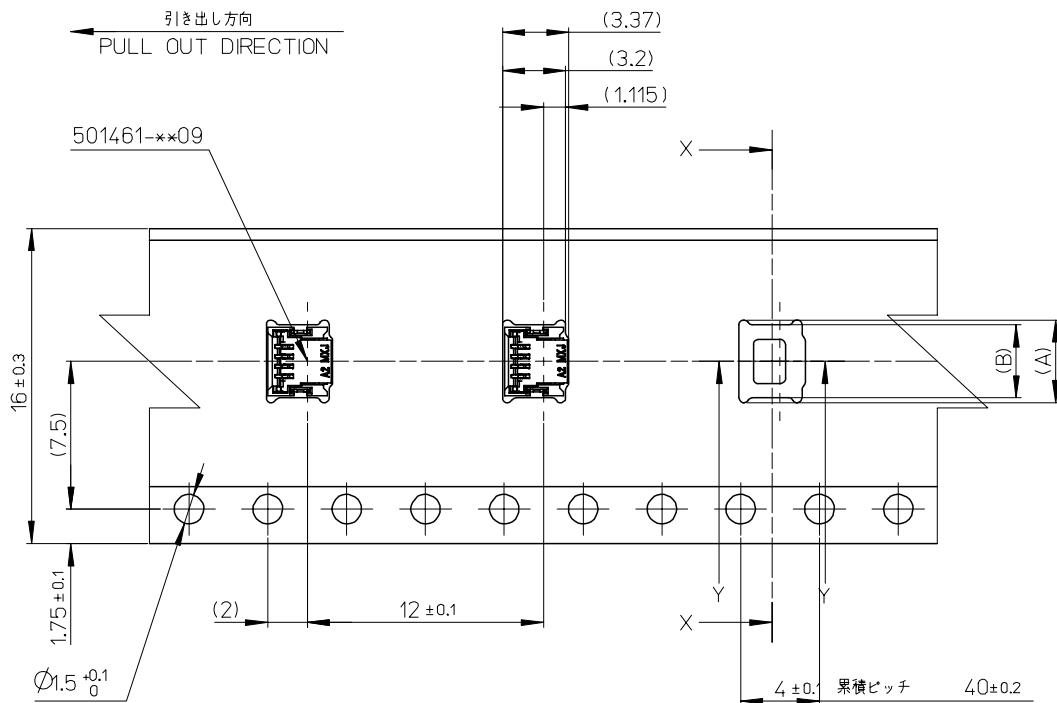
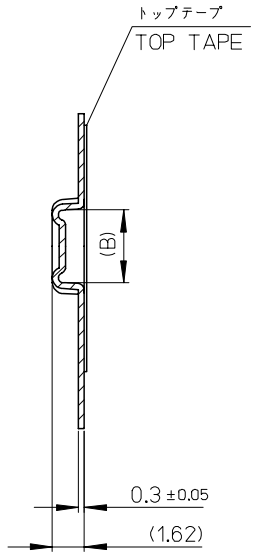
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引き出し方向
PULL OUT DIRECTION



16mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

16	21.4	17.4	5.7	6.2	501461-0801	8	
			5.2	5.7	NOT AVAILABLE	7	
			4.7	5.2	501461-0601	6	
			4.2	4.7	501461-0501	5	
			3.7	4.2	501461-0401	4	
キャリアテープ幅 CARRIER TAPE WIDTH		D	C	(B)	(A)	MATERIAL NO.	極数 CIRCUITS

REVISED EC NO: J2006-2822 DRWR:RSUMIYA 2006/03/08 CHKD:HIRATA 2006/03/08 APPR:HIRATA 2006/03/10	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY RSUMIYA	DATE 2005/02/07	TITLE 0.5 FPC CONN BACK FLIP H=0.8 EMBSTP PKG -LEAD FREE-		
	10 OVER 30 UNDER	± 0.25	CHECKED BY HIRATA	DATE 2005/02/07	MOLEX INCORPORATED		
	30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2005/02/07	DOCUMENT NO. SD-501461-002		
	ANGULAR	± 1	MATERIAL NO. SEE CHART		SHEET NO. 2 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					